



# 苏州群力欣光电科技有限公司

Suzhou Que-lesion Optoelectronic Technology co.,Ltd

## 产品规格书

## SPECIFICATION

客户名称 Customer		产品名称 Product	3528LED
客户料号 Customer No.		产品型号 Type	QSTRGB4-15-20MA
规格书编号 SPEC No	20150411001	日期 Date	2015.04.11

客 户 确 认 APPROVED SIGNATURES		

制定(DRAW): \_\_\_\_\_ 审核(CHECK): \_\_\_\_\_ 批准 (APPROVE): \_\_\_\_\_

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## QSTRGB4-15-20MA

### 特征 Features

- 宽的发光角度  
Extremely wide viewing angle
- 适合所有 SMT 组装和焊接过程  
Suitable for all SMT assembly and solder process
- 可用在载带及卷轴上  
Available on tape and reel
- 防潮等级:2 级  
Moisture sensitivity level: Level 2
- 包装:2000pcs/卷  
Package:2000pcs/reel
- 符合欧盟 RoHS 标准  
RoHS compliant

### 描述 Description

绿光 LED 由 AlGaInP 四种元素芯片激发而成

The green source color devices are made with AlGaInP on Substrate Light Emitting Diode

### 应用 (Applications)

光学指示

Optical indicator

室内显示

Indoor display

汽车照明

Automotive lighting

LCD 背光、转换器, 开关和标志, 显示器等 Backlight for LCD , switch and symbol , display

用于日光灯管

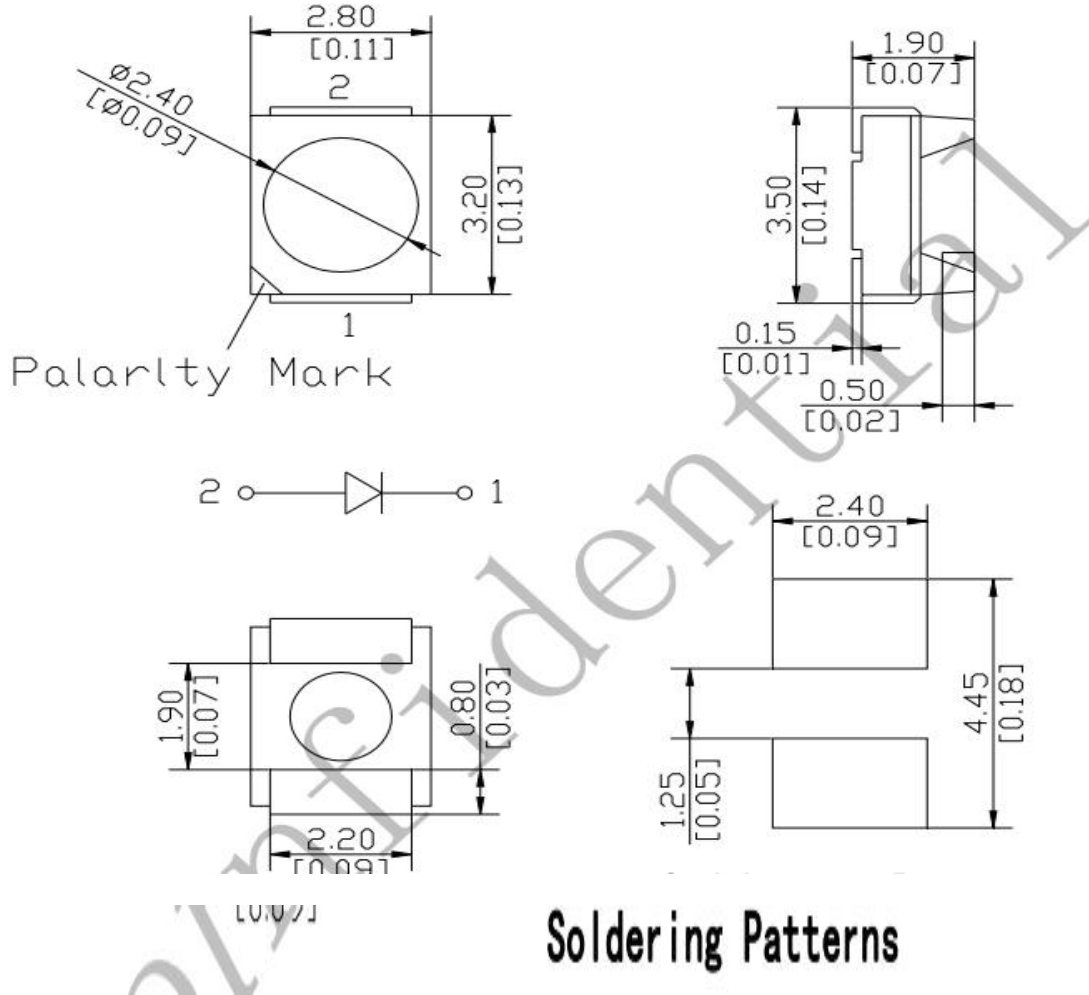
Tubular light application

一般应用

General use

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Package Dimension



Soldering Patterns



NOTES:

1. All dimensions are in millimeters (inches);
2. Tolerances are  $\pm 0.2\text{mm}$  (0.008inch) unless otherwise noted.

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Electrical / Optical Characteristics at Ta=25°C 电性与光学特性

Item 项目	Symbol 符号	test condition 测试条件	Value			unit 单位	
			Min.	Max.	Typ.		
Forward Voltage	Rank G1	Vf	IF=20mA	2.8	2.9	---	V
	Rank G2			2.9	3.0	---	V
	Rank H1			3.0	3.1	---	V
	Rank H2			3.1	3.2	---	V
	Rank I1			3.2	3.3	---	V
	Rank I2			3.3	3.4	---	V
	Rank J1			3.4	3.5	---	V
Dominant wavelength	Rank D10	λd	IF=20mA	520.0	522.5	---	nm
	Rank D20			522.5	525.0	---	nm
	Rank E10			525.0	527.5	---	nm
	Rank E20			527.5	530.0	---	nm
Luminous intensity	Rank 1CN	IV	IF=20mA	900	1200	---	mcd
	Rank M10			1200	1500	---	mcd
	Rank M20			1500	1800	---	mcd
Reverse Current	VR=5V	IR	---	10	---	uA	
Viewing Angle	2Θ1/2	IF=20mA	---	---	120	Deg	
Thermal resistance	Rth(j-s)	IF=20mA	---	---	80	°C/W	

Absolute Maximum Ratings at Ta=25°C 绝对最大值

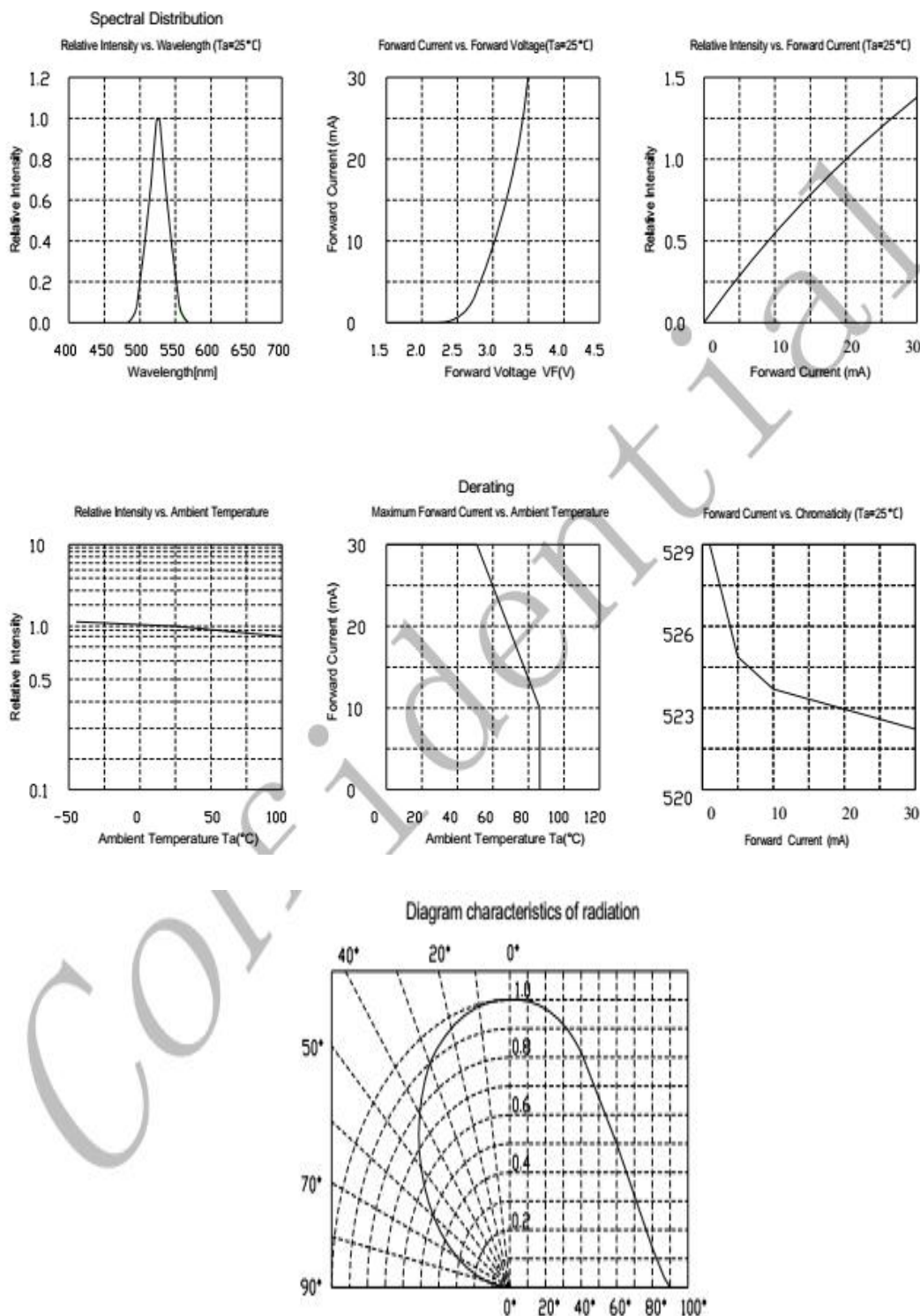
Parameter (参数)	Symbol (符号)	Rating (值)	Units (单位)
Power Dissipation (功耗)	Pd	100	mW
Forward Current (正向电流)	IF	30	mA
Peak Forward Current (峰值电流)	IFP	100	mA
Reverse Voltage (反向电压)	VR	5	V
Electrostatic Discharge(HBM) (静电)	ESD	2000	V
Operating Temperature (操作温度)	Topr	-40 ~ +85	°C
Storage Temperature (储存温度)	Tstg	-40 ~ +100	°C
junction temperature (结温)	Tj	115	°C

Note:

- 1/10 Duty cycle, 0.1ms pulse width. 脉宽0.1ms, 周期1/10.
- The above forward voltage measurement allowance tolerance is 0.1V. 以上所示电压测量误差0.1V.
- The above wavelength measurement allowance tolerance is ±1nm. 以上所示波长测量误差±1nm.
- the above luminous intensity measurement allowance tolerance ±10%. 上述发光强度的测试允许公差为±10%.
- Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product. 使用功率不能超过规定的最大值.
- All measurements were made under the standardized environment of Refond. 所有测试都是基于瑞丰现有的标准测试平台.
- When the LEDs are in operation the maximum current should be decided after measuring the package temperature, junction temperature should not exceed the maximum rate.LED使用的最大电流需要根据散热条件确定, 结温不能超过最大值.

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### ◆ Typical optical characteristics curves 典型光电特性曲线







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**Reliability Test Items And Conditions** 信赖性测试项目及条件

Test Items 项目	Ref.Standard 参考标准	Test Condition 测试条件	Time 时间	Quantity 数量	Ac/Re 接收/拒收
Reflow 回流焊	JESD22-B106	Temp:260°C max T=10 sec	2times.	22Pcs.	0/1
Temperature Cycle 温度循环	JESD22-A104	100°C 30 min. ↑↓5 min -40°C 30 min.	100 Cycles	22Pcs.	0/1
Thermal Shock 冷热冲击	JESD22-A106	-40°C 15min ↑↓ 100°C 15min	300 cycle	22Pcs.	0/1
High Temperature Storage 高温保存	JESD22-A103	Temp:100°C	1000Hrs.	22Pcs.	0/1
Low Temperature Storage 低温保存	JESD22-A119	Temp:-40°C	1000Hrs.	22Pcs.	0/1
Life Test 常温通电	JESD22-A108	Ta=25°C IF=20mA	1000Hrs.	22Pcs.	0/1
High Temperature High Humidity Life Test 高温高湿通电	JESD22-A101	60°C / 90%RH IF=20mA	1000Hrs.	22Pcs.	0/1

**Criteria For Judging Damage** 失效判定标准

Test Items 项目	Symbol 符号	Test Condition 测试条件	Criteria For Judgement 判定标准	
			Min. 最小	Max. 最大
Forward Voltage 正向电压	VF	IF=20mA	-	U.S.L*)x1.1
Reverse Current 反向电流	IR	VR = 5V	-	U.S.L*)x2.0
Luminous Intensity 发光强度	mcd	IF=20mA	L.S.L*)x0.7	-

U.S.L: Upper standard level 规格上限 L.S.L: Lower standard level 规格下限

Note: 备注

The Reliability tests are based on Refond existing test platform. 信赖性测试基于瑞丰现有的测试平台。

The technical information shown in the data sheets are limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license. 以上技术数据仅为产品的典型值，只作为参考，不作为任何应用条件及应用方式的保证。

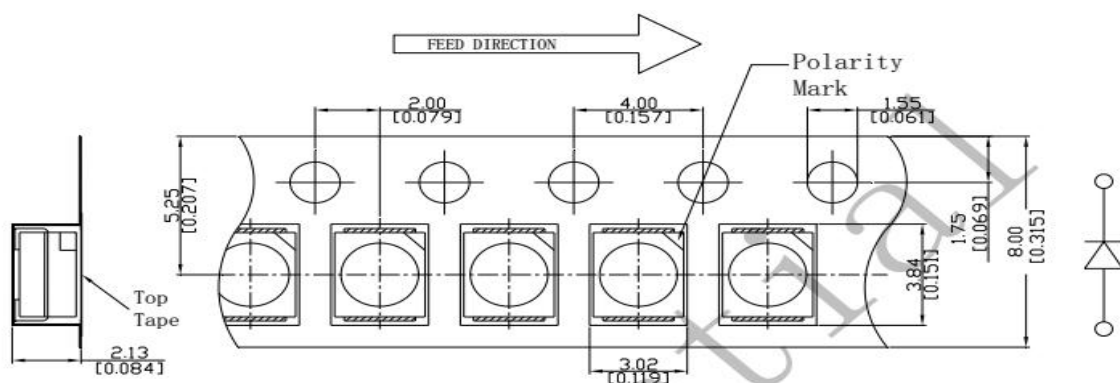
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### 包装 Packaging

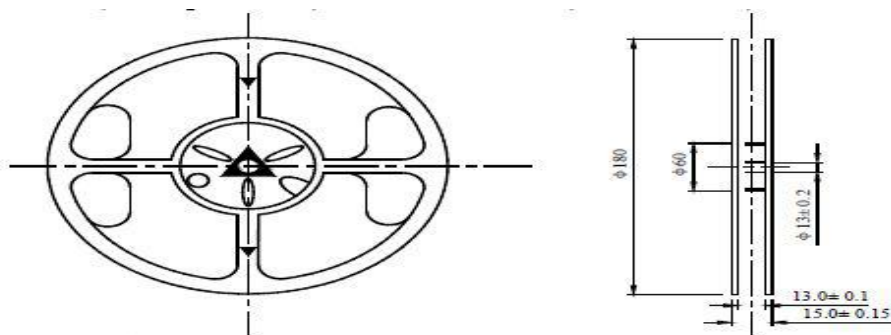
#### 标签 Label

料号 Part No.:\*\*\*      批号 Lot No.:\*\*\*      数量 O'ty(pcs):\*\*\*  
 亮度 Iv(mcd):\*\*\*      波长 (nm) :\*\*\*      电压 VF (v) :\*\*\*  
 日期 Date:\*\*\*

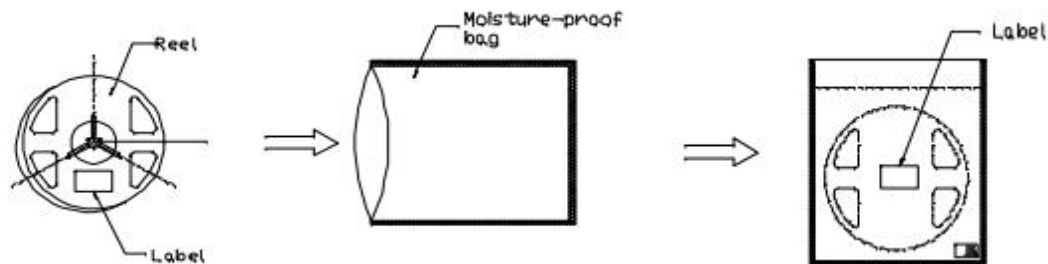
### 载带规格 (单位: mm) Tape Specifications(Units:mm)



### 卷轴尺寸 Reel Dimensions



### 防潮袋包装 Moisture Resistant Packaging



备注: 标注公差为 $\pm 0.1$ mm,单位: mm

Note : The tolerances unless mentioned is  $\pm 0.1$ mm,Unit:mm

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## 焊接指导 Guideline for Soldering

**Soldering iron 烙铁焊接**

1. When hand soldering, keep the temperature of iron below less 300°C less than 3 seconds

当手工焊接时，烙铁的温度必须小于300℃，时间不可超过3秒

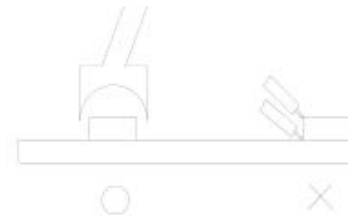
2. The hand solder should be done only one times

手工焊接只可焊接一次

**Repairing 修补**

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or will not be damaged by repairing.

LED回流焊后不应该修复，当修复是不可避免时，必须使用双头烙铁（如下图），但必须事先确认此种方式会或不会损坏LED本身的特性。

**Cautions 注意事项**

The encapsulated material of the LEDs is silicone. Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be influence to the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when use the picking up nozzle, the pressure on the silicone resin should be proper.

LED封装为硅胶，故LED胶体表面较软，用力按压胶体表面会影响LED可靠性，因此应有预防措施避免在封装的零件上的强大压力，当使用吸嘴时，胶体表面的压力应是恰当的。

3. Do not stack together assembled PCBs containing LEDs. Impact may scratch the silicone lens or damage the internal circuitry

不可将模组材料堆积在一起，它可能会损坏内部电路

4. Not suitable to operate in acidic environment, PH<7

不可用在PH<7的酸性场所

